September 1 2007
Tokyo Eletech Corporation

Notes in Handling BGA adapters, CSPACK

1.) CSPACK are encapsulated in vacuum plastic bags to prevent the solder bumps from oxidation. CSPACK must be soldered on PC boards within the day when the packing box is opened. If CSPACK are not soldered on PC boards for more than 24 hours after opened the bags, CSPACK should be kept in a desiccators.

2.) A light green protection spacer and top cover are fixed with screws onto CSPACK to prevent the pogo pins from bent or damage. Then CSPACK are encapsulated in vacuum plastic bags as mentioned item 4. The spacer and top cover should remain unscrewed until soldering process is completed, in order to prevent the contact pins from floating flux in a SMT chamber.

3.) Recommend soldering temperature profile on the surface of CSPACK:
Preheat : 150 to 180℃ for 180 seconds
Reflow : 210℃ for 30 seconds max.
Peak temperature : 240℃ for 10 seconds（Sn—Pb）

4.) CSPACK should not be cleansed. Cleaning materials will contaminate in the CSPACK due to its construction.

5.) When fixing CSPACK with a screwdriver, the precision driver (+ type) #0 or 1, or a torque driver should be used. Four screws at the corners should loosely fasten first, then tightly fasten the screws. If only one screw is tightly fastened more than others, open contact problem might be caused.

6.) Guide pins come out about 1.4 mm from the bottom surface of PCB of 1.6 mm thickness, when a guide pin type CSPACK is soldered. If any force is applied to the pins come out, the force is transferred to solder bumps of the bottom of CSPACK. This may cause open contact problems, or may damage CSPACK. So please protect the pins come out from any force.

CSPACK were developed for test or emulation applications.

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